Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**SOURCE**

**G**

**.070”**

**.070”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: G = .006 X .010” S = .011” X .013”**

**Backside Potential: DRAIN**

**APPROVED BY: DK DIE SIZE .070” X .070” DATE: 4/27/23**

**MFG: SUPERTEX/MICROCHIP THICKNESS .011” P/N: TPS2640ND**

**DG 10.1.2**

#### Rev B, 7/1